

327,00mm

41,00mm

# CB L3 v1.3.1 - 0.5mm 5-Layer Board with Polyimide (UT901) Dielectric Layers and Blind Vias

## Material Selection

Polyimide UT901  
 Permittivity @ 100MHz:  
 Permittivity @ 1GHz:  
 Loss Tangent @ 100MHz:  
 Loss Tangent @ 1GHz:  
 Lead Free Assembly Compatible

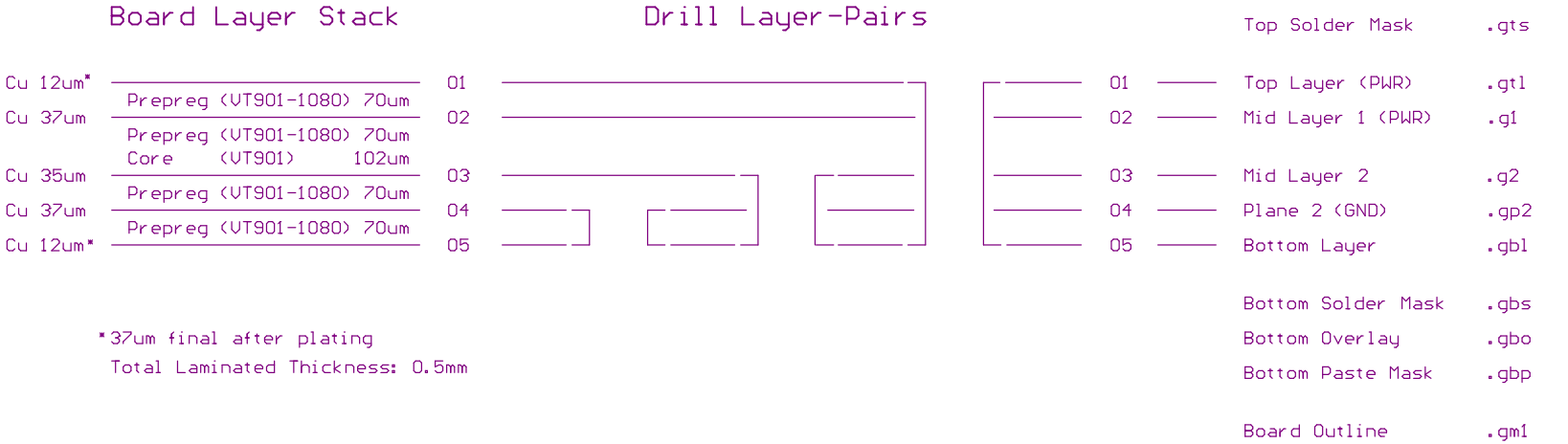
Solder resist colour: green  
 Silkscreen print colour: white

## Surface Finish

On top and bottom layer surfaces:  
 electroless nickel immersion gold

## Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.  
 For them we do not care the finished hole sizes.



## Holes / Drilling

Drill files contain finished hole diameters  
 Drilling layer pairs: 4-5, 3-5, 1-5

## Board Outline

Contour routed with break-away tabs

## Element Counts

(for reference only)

Components: 156  
 Nets: 211  
 Pads: 1181  
 Tracks: 7880  
 Polygons: 34  
 Holes: 897  
 Vias: 849

## Controlled Impedance Reference

Diff. trace width/space on middle layer2 (stripline) 75 ohms +/- 10% : 0.100/0.100mm  
 Diff. trace width/space on middle layer2 (stripline) 60 ohms +/- 10% : 0.150/0.100mm  
 Diff. trace width/space on bottom layer (microstrip) 75 ohms +/- 10% : 0.125/0.100mm  
 Diff. trace width/space on bottom layer (microstrip) 60 ohms +/- 10% : 0.175/0.100mm